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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.:
NSC1P217D2/NS-3877-2

Application No.: 09/625,071

Examiner: Clark, S.

Filed: July 25, 2000

Group: 2815

Title: LEAD FRAME CHIP SCALE PACKAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on November 30, 2004 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed:

[Handwritten signature: Lara M. Nelson]
Lara M. Nelson

REQUEST FOR STATUS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby requests status of the above-referenced patent application. The Issue Fee was paid on June 11, 2004 and no response has been received as of this date.

Respectfully submitted,

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